

SINGLE-CHIP MICROCONTROLLER

The μ PD17102 is a four-bit single chip microcontroller which has a built-in LCD controller, D/A converter, and operational amplifier. This CPU uses the μ PD17000 architecture, allowing data transfer and operation between data memory areas or between data memory areas and peripheral circuits with only one instruction. It also supports 16-bit (1-word) instructions.

FEATURES

μPD17000 architecture

• Program memory (ROM) : 4K bytes (2048 x 16 bits)

• Data memory (RAM) : 208 words (208 x 4 bits)

Command execution time : 2.0 μs (8 MHz, ceramic/crystal oscillator)

• Interrupting function (Internal: 3, and external: 2)

• 8-bit timer/counter : 2 channels (built-in modulo)

• 8-bit serial interface

2-channel complete CMOS operational amplifier
 (Two operation modes available: NORMAL and SAMPLE/HOLD)

- 4-channel multiplexer input comparator --
- 6-bit D/A converter
- Feasible to realize the 4-channel 6-bit A/D conversion function using the above-mentioned comparator and D/A converter
- LCD controller/driver
 (14SEGMENT x 2COMMON, 13SEGMENT x 3COMMON, and 12SEGMENT x 4COMMON)
- Zero-cross detection selectable
- Standby function (Stop/Halt)

USE:

Electronic rice cooker and blood pressure meter, etc.

ORDERING INFORMATION

Order Code	Package Package
μPD17102G-XXX-00	52-pin plastic QFP (bent lead)
μPD17102G-XXX-03	52-pin plastic QFP (straight lead)



OUTLINE OF FUNCTIONS

μPD17000 architecture

Program memory (ROM): 4K bytes (2048 x 16 bits)
 Data memory (RAM) : 222 words (222 x 4 bits)

• Stack level : 3 levels

• Instruction cycle : 2 µs (when operated at 5.0 V and 8 MHz)

e Interrupting function : (Internal: 3, and external: 2)
e 8-bit timer/counter : 2 CH (with modulo integrated)

8-bit serial interface

2-channel complete CMOS operational amplifier

(Two operation modes available: NORMAL and SAMPLE/HOLD)

e 4-channel input comparator with multiplexer

6-bit D/A converter

Feasible to realize 4-channel, 6-bit A/D conversion function using the above-mentioned comparator and D/A converter.

● LCD controller (14SEGMENT x 2COMMON, 13SEGMENT x 3COMMON, and 12SEGMENT x 4COMMON)

Zero-cross detecting function

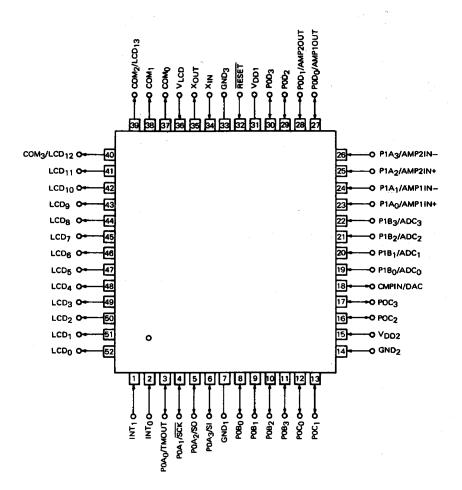
• Standby function (STOP/HALT)

Data/memory low supply voltage holding function

Oscillator circuit for system clock (ceramic and crystal)

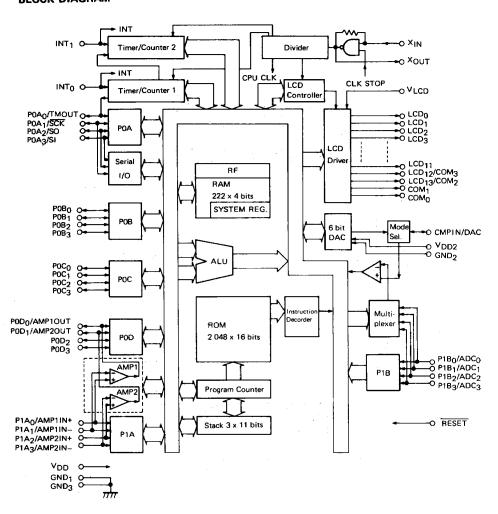
Single power unit (3.0 to 6.0 V, but 4.5 to 6.0 V when the operational amplifier is used)

PIN CONFIGURATION (Top View)





BLOCK DIAGRAM





1. OUTLINE

The μ PD17102 is a 4-bit single chip microcontroller which integrates all the following circuits on one chip: 4-bit ALU, program memory (ROM), data memory (RAM), I/O ports, timer/event counter, serial interface, vector interrupt circuit.

This chip using the µPD17000 Series architecture has various built-in peripheral circuits including analog circuits, allowing the user to incorporate it into electrical appliances and intelligent units in a distributed system for home automation.

For program development, NEC supports the in-circuit emulator (IE-17K), so that the user can debug programs easily by using the emulator together with the SE board for each product.



2. PIN FUNCTIONS

2.1 Input/Output Ports

2.1.1 POA₀ to POA₃ (Port OA): Bi-directional input/output ports

Port 0A is a 4-bit input port (pins from P0A₀ to P0A₃) with output latch circuits.

This port is mapped to 70H at bank 0 in the data memory space and accessed with normal data memory operation instructions. The direction of input/output is switched for all four bits by the POAGIO value. Setting POAGIO to "1" outputs the value stored at 70H of bank 0 to the pin and setting to "0" disables output and sets input mode. Regardless of the POAGIO value, the pin status can be read with a data memory reference instruction. The contents of the output latch remain unchanged unless the data at 70H of bank 0 is rewritten.

POA₀ is shared by the timer 1 output pin TMOUT. It operates as TMOUT when PTOUTON in the register file is "0" and in normal input/output mode.

When TMOUT is selected, this pin outputs "1" at time 1 reset and reverses the output each time the timer 1 value matches the contents of the modulo register. At this time, this pin is set in output mode regardless of the POAGIO value. The pin status at this time can also be read with a data memory reference instruction. The output latch as POA₀ is independent of TMOUT, and therefore data can be written to 70H of bank 0 even if the pin operates as TMOUT and the data is output when PTOUTON is set to "0" while POAGIO is "1."

POA₁ to POA₃ are shared by SCK, SO, and SI of the serial interface. The PAO pin is set in normal input/output mode when the SIOON value in the register file is "0" and used as the SIO pin when it is "1."

In the port OA input/output format, either of the Nch open/drain input/output or Nch open/drain input/output with a built-in pull-up resistor is selectable by the mask option. In Nch open/drain input/output mode, the port has a 9 V withstanding voltage and is suitable for an interface with a circuit using a different supply voltage. By using the Nch open/drain input/output structure, a 2-wire serial interface can also be used.

When SIOON is "1," data cannot be output to the SCK and SO pins as a port. Even if data is transferred to address 70H of bank 0, this data cannot be input to POA₁ to POA₃. At this time, only POA₃ is available.

When the \overline{SCK} pin is in input mode, however, data can be written to the P0A₁ output latch.



Table 2-1 Port 0A functions

DTOUTON	SIGON	macio	Write to bank	Read from		Pin fu	nction	
PTOUTON	SIOON	POAGIO	0, 7 0 H	bank 0, 70H	POA ₀	POA ₁	P0A ₂	P0A ₃
0	0	0	All four bits are valid.		POA ₀ IN	POA ₁	POA ₂	POA ₃ IN
		1	All four bits are valid.		P0A ₀ OUT	POA ₁ OUT	P0A ₂ OUT	P0A ₃ OUT
	1	0	Only POA ₀ is valid.	Enable.	POA _O	SCK	so	SI
		1	Only POA ₀ is valid.		P0A ₀ OUT	SCR SC	30	
1	0	0	All four bits are valid	(Pin status)		POA ₁	POA ₂ IN	POA ₃
		1	All four bits are valid.			P0A ₁ OUT	POA ₂ OUT	P0A ₃
	•	0	Only POA ₀ is valid.	1	TMOUT	SCK	so	6.
	1	1	Only POA ₀ is valid.			SUR	30	SI

Note: If data is written to 70H of bank 0 when SIOON is "1," this data can be written to POA₁ only when the SCK pin is in input mode.

2.1.2 POB₀ to POB₃ (port OB), POC₀ to POC₃ (port OC): Bi-directional input/output

Ports 0B and 0C are 4-bit input/output pins with output latch circuits: From P0B₀ to P0B₃ and from P0C₀ to P0C₃. These ports are mapped to 71H and 72H of bank 0 in the data memory space, respectively and are accessed with normal data memory operation instructions like port 0A. The direction of input/output is switched for all 4-bits by the P0BGIO or P0CGIO value in the register file. Setting the value to "1" outputs the data at 71H or 72H of bank 0 to the corresponding pin and "0" disables the output and sets the input mode. Regardless of the P0BGIO and P0CGIO values, the pin status is read when a data memory reference instruction is executed. At this time, the contents of the output latch remain unchanged.

The input/output format of ports OB and OC is the CMOS (push/pull) type.

Table 2-2 Functions of ports 0B and 0C

POBGIO POCGIO	Input/output direction of pin	Write to bank 0, 71H or 72H	Read from bank 0, 71H or 72H		
0	Input (output disable)				
1	Output	Available	Available (pin status input)		



2.1.3 POD₀ to POD₃ (port D): Bi-directional input/output

Port 0D comprises 4-bit input/output pins with output latch circuits. It is mapped to 73H of bank 0 in the data memory space. The input/output direction is switched by the PODGIO value in the register file.

POD₀ is shared with the AMP1 output pin AMP1OUT, and POD₁ is shared with the AMP2 output pin AMP2OUT. These bits are used in normal input/output mode when the AMP1EN or AMP2EN values in the register file are "0" and as AMP1OUT and AMP2OUT respectively when the values are "1."

When AMP10UT and AMP20UT are selected, the pins are used as the AMP10UT and AMP20UT output pins, regardless of the P0DGIO value. A data memory reference instruction reads the pin status regardless of the function selected for the pin. At this time, the pin potential is intermediate, the read value is undefined. The μ PD17102 reads only at the moment the instruction is executed and disables other input circuits. Therefore, the through current does not flow through the input circuit.

The POD₀ and POD₁ output latch circuits are independent of AMP1OUT and AMP2OUT. Therefore, data can be written to bank 0, 73H by setting AMP1EN and AMP2EN to "1" even if the pins operate as AMP1OUT and AMP2OUT. When PODGIO is "1," the pins output data as a port by setting AMP1EN and AMP2EN to "0."

The port 0D input/output format is CMOS (push/pull) input/output.

Pin function Read from Write to AP1EN PODGIO bank 0, 73H bank 0, 73H POD₁ POD₂ POD₃ AP2EN POD_o POD₁ IN POD₂ IN POD₃ IN POD₀ IN 0 0 POD₁ OUT POD₂ OUT POD₃ OUT POD₀ OUT 1 All four bits Enable. POD₃ IN are valid. Pin status. POD₂IN 0 AMP2OUT AMP1OUT 1 POD₂ OUT POD₃ OUT 1

Table 2-3 Port 0D functions

Note: The AMP output control is selectable for AMP1/2 separately.

2,1,4 P1A₀ to P1A₃ (port 1A): Input

Port 1A comprises 4-bit input pins.

It is mapped to 70H of bank 1 in the data memory space.

P1A₀ and P1A₁ are shared with AMP1 non-reverse input (AMP1IN+) and reverse input (AMP2IN-), P11A and P1A3 are shared with AMP2 non-reverse input (AMP2IN+) and reverse input (AMP2IN-). These pins are not switched and are always connected to both input circuits of the operator amplifier (analog input) and port (digital input).

When used as analog input pins, apply an intermediate potential or AC voltage. If a data memory reference instruction is executed at this time, an undefined value is read. Similar to port 0D, the through current does not flow through the input circuit.

Port 1A has three mask options: With pull-up resistor, with pull-down resistor, and with no built-in resistor. When the pins are used as analog input pins, select the mask option for no built-in resistor. Otherwise, the pins may not operate normally.

Output instructions to the port (data write to 70H in bank 1) are invalid.



Table 2-4 Port 1A function

Read from bank 1, 70H (logical input)	Write to bank 1, 70H	Analog input
Enable		
(Pin status input)	Disable	Always connected to AMP input.
(Undefined at intermediate potential)		

2.1.5 P1B₀ to P1B₃ (port 1B): Input

Port 1B comprises 4-bit input pins.

It is mapped to 71H of bank 1 in the data memory space.

Only one of these pins can be set as the input pin of the non-reserve input from the comparator by ADCCH0 and ADCCH1. For more information, see Section 3.12. Similar to ports 0D and 1A, the pin status of port 1B is read with the data memory reference instruction, regardless of the selected pin function, and the through current does not flow through the input circuit even if the intermediate potential is applied.

Port 1B also has three mask options: With pull-up resistor, with pull-down resistor, and with no built-in resistor. When the pins are used as analog input pins, select the mask option for no built-in resistor. Otherwise, the pins may not operate normally.

Output instructions to port 1B (data write to 71H in bank 1) are invalid.

Table 2-5 Port 1B function

Read from bank 1, 71H (logical input)	Write to bank 1, 71H	Analog input
Enable		Either pin is connected to
(Pin status input)	Disable	the comparator input
(Undefined at intermediate potential)		(by ADCCH0 and ADCCH1).

2.2 INT₀, INT₁

INT₀ and INT₁ are interrupt request input pins for which the active rising or falling edge is selectable by IEG₀ and IEG₁. At the rising or falling edge of the INT₀ or INT₁ signal selected by IEG₀ and IEG₁, the interrupt request flag (IRQ0, IRQ1) is set.

To prevent malfunctions from noise, the pins has a built-in noise remover. The status of the pin for which noise is eliminated by the noise remover is read by referencing INT_0 and INT_1 in the register file with the PEEK instruction, so that the pins are simply used as input pins.

In addition, INT₀/INT₁ are the count clock input pins of timer 1/2, respectively, and are used when external clocks are selected as timer count clock sources. When sharing the timer input and INT₀/INT₁ interrupt request input, note that the INT₀/INT₁ interrupt request flag is also set by the clock.

The INT₁ pin is also used to detect zero-cross when ZCROSS in the register file is set to "1."

2.3 CMPIN/DAC, VDD2, GND2

 V_{DD2} and GND_2 are pins used to apply the reference voltage of the built-in 6-bit D/A converter. Apply the V_{DD} potential to V_{DD2} and the GND potential to GND_2 . These two pins are separated from V_{DD} and GND and can have separated digital and analog power sources. The applied voltage between the pins is divided into 26 steps (64 steps). The analog value corresponding to digital data stored in four bits of 72H and high-order two bits of 73H of bank 1 in the data memory space is the D/A converter output.

To output the D/A converter data from the CMPIN/DAC pin, set DACEN to "1" and CMPEN to "0" in the register file.



To use a comparator, set DACEN to "0" and CMPEN to "1" in the register file. At this time, the CMPIN/DAC pin operates as the reverse input pin of the comparator (CMPIN). Apply a voltage with the same potential as V_{DD} to the V_{DD2} pin. Also apply the same potential to GND₂ pin to minimize the current flowing through the D/A converter which is not used.

When using the 6-bit D/A converter under program control, set DACEN to "1" and CMPEN to "1" in the register file. At this time, D/A converter data is not output externally, but is directly input to the comparator reverse input pin. Therefore, the CMPIN/DAC pin is not used.

Table 2-6 V_{DD2}, GND₂, and CMPIN/DAC functions

DACEN	CMPEN	V _{DD2}	GND ₂	CMPIN/DAC	Function
-		V _{DD} potential	V _{DD} potential	V _{DD} potential	D/A converter and comparator are not used.
0	0	V _{DD2}	GND ₂	High impedance	Initial state when the D/A converter is used (Note).
0	1	V _{DD} potential	V _{DD} potential	CMPIN	When the comparator is used.
1	0	V _{DD2}	GND ₂	DAC	When the D/A converter is used
1	1	V _{DD2}	GND ₂	V _{DD} potential	Used as D/A converter

 $[\]mbox{V}_{\mbox{\scriptsize DD}}$ potential indicates that $\mbox{V}_{\mbox{\scriptsize DD}}$ potential is applied externally.

Note: DACEN and CMPEN are set to "0" at reset.

2.4 V_{LCD}

V_{LCD} is a power supply pin for driving the liquid crystal display panel (LCD panel).

Depending on the bias method used, it generates the 1/2 V_{LCD} , 1/3 V_{LCD} , and 2/3 V_{LCD} voltages. When using LCD₀ to LCD₁₃ as the output pins, apply the high voltage under the supply voltage (V_{DD}).

2.5 LCD₀ to LCD₁₁, COM₃/LCD₁₂, COM₂/LCD₁₃, COM₁, COM₀

LCD₀ to LCD₁₁, COM₃, LCD₁₂, COM₂/LCD₁₃, COM₁, and COM₀ are LCD panel segment driver pins used to select drive method, such as 14-segment 2-common, 13-segment 3-common, 12-segment 4-common.

LCD₀ to LCD₁₃ are used as output pins when LCDEN in the register file is "0." At this time, COM₁ and COM₀ are not used.

For more information on the LCD panel, see Section 3.10.

Table 2-7 LCD₀ to LCD₁₁, COM₃/LCD₁₂, COM₂/LCD₁₃, COM₁, and COM₀ functions

LCDEN	LCD ₀ to LCD ₁₁ , COM ₃ /LCD ₁₂ , COM ₂ /LCD ₁₃	COM ₁ , COM ₀
0	All are output pins.	Not used
1	LCD drivers and common drivers	Common drivers

2.6 XIN, XOUT

 X_{IN} and X_{OUT} are pins used to connect the oscillation vibrator in the system clock generator.

2.7 RESET

RESET is a low-level active reset input pin. The reset has priority over all other operations. In addition to CPU initial start, this pin is also used to release standby mode.



2.8 V_{DD1}

V_{DD1} is a positive power supply pin.

2.9 GND₁, GND₂

 GND_1 and GND_2 are GND potential pins. Wire them so that the same potential is used externally.

2.10 Pin Mask Options

The μ PD17102 pins have the mask options listed below. These option can be selected bit according to purpose.

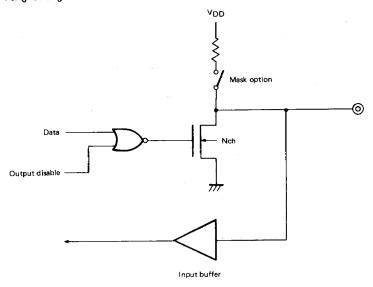
Pin name	Mask option
POA ₀ to POA ₃	(1) Nch open-drain input/output (2) Nch open-drain plus built-in pull-up resistor input/output
P1A ₀ to P1A ₃ P1B ₀ to P1B ₃	(1) No built-in resistor(2) Built-in pull-up resistor(3) Built-in pull-down resistor
INT ₀	(1) No built-in resistor(2) Built-in pull-up resistor(3) Built-in pull-down resistor
RESET	(1) No built-in resistor (2) Built-in pull-up resistor



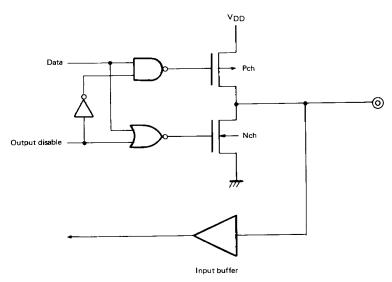
2.11 Pin Input/Output Circuits

The Input/output circuit of each pin of the $\mu PD17102$ is shown below in a partly simplified format:

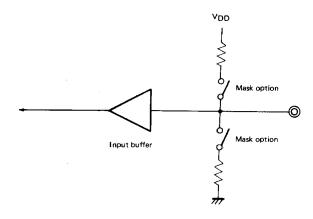
(1) POA₀ to POA₃



(2) $\ \ \ \mathsf{POB}_0$ to POB_3 , POC_0 to POC_3 , POD_0 to POD_3



(3) $P1A_0$ to $P1A_3$, $P1B_0$ to $P1B_3$, INT_0 , INT_1



(4) RESET

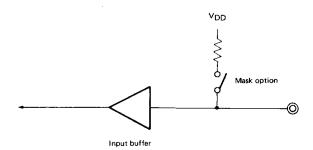




Table 2-8 Digital input/output port pin functions

PIN NAME	1/0	COMBINED USE	FUNCTION	WHEN RESET	
P0A ₀		TMOUT			
POA ₁	1	SCK	4-bit I/O port (port 0A)	High impedance (POAn input	
POA ₂	Input/output	so	4-Dit 1/O port (port 0A)	Tagy Impossition (For at Impos	
P0A ₃	1	SI			
POB _O to POB ₃	Input/output		4-bit I/O port (port 0B) Large current (15 mA)	High impedance (input)	
P0C ₀ to P0C ₃	Input/output		4-bit I/O port (port 0C) Large current (15 mA)	High impedance (input)	
POD _O		AMP1OUT		High impedance (PODn inpu	
POD ₁	Input/output	AMP2OUT	4-bit I/O port (port 0D)	Trigit impossition (1 050 mp	
POD ₂ to POD ₃	1		Middle current (10 mA)	High impedance (input)	
P1A ₀		AMP1 IN+			
P1A ₁	1	AMP1IN-	4-bit input port (port 1A)	Input	
P1A ₂	Input	AMP2IN+	4-bit input port (port TA)	Input	
P1A3	7	AMP2IN-			
P1B ₀		ADC ₀			
P1B ₁	1	ADC ₁	4-bit input port (port 1B)	Input	
P1B2	Input	ADC ₂	4-pit hiput port (port 16)	Impor	
P1B3		ADC ₃			



Table 2-9 Pins other than port pins

Pin name	Input/output	Shared	Function	At reset	
INT ₀	Input		Used as both the timer 1 count clock input pin and the external interrupt input pin.	Input	
INT ₁	Input		Used as the timer 2 count clock input pin and external interrupt input pin. Zero-cross detection function is selectable.	Input	
TMOUT	Output	POA _O	Timer 1 output pin	POA ₀ input	
SCK	Input/output	POA ₁	Serial clock input/output pin	POA ₁ input	
SO	Output	POA ₂	Serial data output pin	POA ₂ input	
SI	Input	POA ₃	Serial data input pin	POA ₃ input	
AMP1OUT	Output	POD ₀	AMP1 output pin	POD ₀ input	
AMP2OUT	Output	POD ₁	AMP2 output pin	POD ₁ input	
AMP1IN+		P1A ₀	AMP1 non-reversed input pin		
AMP1IN-			AMP1 reversed input pin		
AMP2IN+	Input	P1A ₂	AMP2 non-reversed input pin	Input	
AMP2IN-		P1A ₃	AMP2 reversed input pin	1	
ADC ₀ to ADC ₃	Input	P1B ₀ to P1B ₃	Comparator input pin	Input	
V _{DD2}	Input		D/A converter reference voltage input pin (high-potential side)		
GND ₂	Input		D/A converter reference voltage input pin (low-potential side)		
CMPIN	Input/output	DAC	Used as the D/A converter output pin and comparator input pin.	High impedance	
LCD ₀ to	Output	-	LCD segment driver output pin. Also used as the output port.	Output	
сом3	Output	LCD ₁₂	Used as the LCD common driver output and LCD segment driver	Output	
COM ₂		LCD ₁₃	pin. Also used as an output port.	Jupat	
COM ₀ , COM ₁	Output		LCD common driver output pin	Output	
V _{LCD}	Input		LCD driver split potential setting pin	Input	
RESET	Input		System reset input pin	Input	
V _{DD1}	,		Positive power supply pin		
GND ₁ , GND ₃			GND potential pin		
X _{IN} , X _{OUT}			System clock oscillator pin	-	



3. INTERNAL BLOCK

3.1 Program Counter (PC)

The program counter (PC) is an 11-bit binary counter that retains address data of the program memory (ROM).

Fig. 3-1 Program counter configuration

PC10	PC9	PC8	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0

When the RESET signal goes to low, the PC is set to 0.

Usually, the counter is incremented by one each time an instruction is executed.

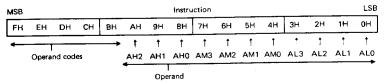
The CALL instruction saves the contents of the counter (return address) to the stack memory then loads the branch destination address to the counter. Return instructions (RET, RETSK, and RETI) load the contents of the stack memory (return address) to the counter. The branch instruction (BR) loads the branch destination address to the counter. The ROM data reference instruction (MOVT) temporarily loads the address at which the data to be referenced is stored to the counter. Take care with the level because the contents of the PC are saved to the stack memory immediately before the address is loaded.

In Fig. 3-2, AHn, AMn, and ALn are addresses indicated by the instruction operand. (See Fig. 3-3.) ARmm is bit n in the address register (ARm) which contains the address to be loaded to the program counter. SP is the stack pointer which points to the contents of the stack memory.

Fig. 3-2 Relationship between instructions and values to be loaded

РСЗ PC2 PC1 PC0 PC6 PC5 PC4 PC10 PC9 PC8 PC7 (SP) (SP) (SP) (SP) (SP) RET, RETSK, RETI (SP) (SP) (SP) (SP) (SP) (SP) ALO AH2 AH1 AH0 АМЗ AM1 AMO AL3 AL2 AL1 BR, CALL AR10 AR03 AR02 AR01 AR00 AR13 AR12 AR11 BR@AR, CALL@AR, MOVT 1 1

Fig. 3-3 Instruction word configuration





7. ASSEMBLER RESERVED WORDS

7.1 Mask Option Pseudo Instructions

For coding μ PD17102 programs, a mask option must be specified in Assembler source programs with the mask option pseudo instruction.

The following pins require the mask option:

- P0A₀, P0A₁, P0A₂, P0A₃
- P1A₀, P1A₁, P1A₂, P1A₃
- P1B₀, P1B₁, P1B₂, P1B₃
- INT₀, INT₁
- RESET

7.1.1 OPTION and ENDOP pseudo instructions

From the OPTION pseudo instruction to the ENDOP pseudo instruction is referred to as the mask option definition block. The format of this block is shown below.

Only the six pseudo instructions explained in Section 7.1.2 can be input to the mask option definition block.

Format:

Symbol field	Mnemonic field	Operand field	Comment field
[level:]	OPTION		[comment:]
	•		
	•		
	•		
	ENDPOP		

7.1.2 Mask option definition pseudo instructions

Table 7-1 lists the pseudo instruction that are allowed in the mask option definition block. An example for defining the mask option is shown below.

Format:

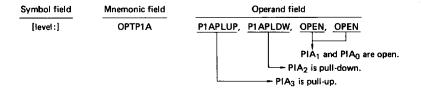




Table 7-1 Mask option definition pseudo instructions

Pin name	Mask option pseudo instruction	Number of parameters	Parameter name		
POA ₀ to POA ₃	OPTP0A	4	POAPLUP : Pull up OPEN : Open		
P1A ₀ to P1A ₃	OPTP1A	4	P1 APLUP : Pull up P1 APLDW : Pull down OPEN : Open		
P1B ₀ to P1B ₃	OPTP1B	4	P1BPLUP : Pull up P1BPLDW : Pull down OPEN : Open		
,INT ₀	OPTINTO .	1	INTOPLUP : Pull up INTOPLDW : Pull down OPEN : Open		
INT ₁	OPTINT1	1	INT1PLUP : Pull up INT1PLDW : Pull down OPEN : Open		
RESET	OPTRES	1	RESPLUP : Pull up OPEN : Open		

7.2 Reserved Symbols

Table 7-2 lists the symbols defined in the μ PD17102 device file. These defined symbols include the control register names, port names, and peripheral device names.

- (1) Control registers in register file
 - The names of the control register assigned to data memory addresses 80H to BFH in bank 0 are defined. These registers are accessible through the window register (WR) with the PEEK and POKE instructions.
- (2) Registers and ports in data memory Registers assigned to data memory addresses 00H to 7FH, and ports and system registers assigned to 70H and after are defined.
- (3) Peripheral circuits
 - Peripheral circuits accessible with the GET and PUT D/A converters are defined.



Table 7-2 List of reserved symbols (1/4)

NAME	ATTRIBUTE	VALUE	R/W	DESCRIPTION		
DBF3	MEM	0.0CH	R/W	Bit 15 to bit 12 of data buffer		
DBF2	MEM	0.0DH	R/W	Bit 11 to bit 8 of data buffer		
DBF1	MEM	0.0EH	R/W	Bit 7 to bit 4 of data buffer		
DBF0	MEM	0.0FH	R/W	Bit 3 to bit 0 of data buffer		
AR3	MEM	0.74H	R	Bit 15 to bit 12 of address register		
AR2	MEM	0.75H	R	Bit 11 to bit 8 of address register		
AR1	MEM	0.76H	R/W	Bit 7 to bit 4 of address register		
AR0	MEM	0.77H	R/W	Bit 3 to bit 0 of address register		
WR	MEM	0.78H	R/W	Window register		
BANK	MEM	0.79H	R/W	Bank register		
IXH	MEM	0.7AH	R/W	Bit 11 to bit 8 of index register		
MPH	MEM	0.7AH	R/W	Bit 7 to bit 4 of memory pointer		
MPE	FLG	0.7AH.3	R/W	Memory pointer enable flag		
IXM	MEM	0.7BH	R/W	Bit 7 to bit 4 of index register		
MPL	MEM	0.7BH	R/W	Bit 3 to bit 0 of memory pointer		
IXL	MEM	0.7CH	R/W	Bit 3 to bit 0 of index register		
RPH	MEM	0.7DH	R/W	Bit 7 to bit 4 of register pointer		
RPL	MEM	0.7EH	R/W	Bit 3 to bit 0 of register pointer		
PSW	MEM	0.7FH	R/W	Program status word		
BCD	FLG	0.7EH.0	R/W	BCD operation flag		
CMP	FLG	0.7FH,3	R/W	Compare flag		
CY	FLG	0.7FH.2	R/W	Carry flag		
Z	FLG	0.7FH.1	R/W	Zero flag		
IXE	FLG	0.7FH.0	R/W	Index register enable flag		
LCDD0	MEM	0.60H	R/W	LCD segment 0		
LCDD1	MEM	0.61H	R/W	LCD segment 1		
LCDD2	MEM	0.62H	R/W	LCD segment 2		
LCDD3	MEM	0.63H	R/W	LCD segment 3		
LCDD4	MEM	0.64H	R/W	LCD segment 4		
LCDD5	MEM	0.65H	R/W	LCD segment 5		
LCDD6	MEM	0.66H	R/W	LCD segment 6		



Table 7-2 List of reserved symbols (2/4)

NAME	ATTRIBUTE	VALUE	R/W	DESCRIPTION
LCDD7	MEM	0.67H	R/W	LCD segment 7
LCDDB	MEM	0.68H	R/W	LCD segment 8
LCDD9	MEM	0.69H	R/W	LCD segment 9
LCDD10	MEM	0.6AH	R/W	LCD segment 10
LCDD11	MEM	0.6BH	R/W	LCD segment 11
LCDD12	MEM	0.6CH	R/W	LCD segment 12
LCDD13	MEM	0.6DH	R/W	LCD segment 13
P0A0	FLG	0.70H.0	R/W	Port 0A bit 0
P0A1	FLG	0.70H.1	R/W	Port 0A bit 1
P0A2	FLG	0.70H.2	R/W	Port 0A bit 2
P0A3	FLG	0.70H.3	R/W	Port 0A bit 3
POBO	FLG	0.70H.0	R/W	Port 0B bit 0
P0B1	FLG	0.71H.1	R/W	Port 0B bit 1
POB2	FLG	0.71H.2	R/W	Port 0B bit 2
POB3	FLG	0.71H.3	R/W	Port 0B bit 3
POCO	FLG	0.71H.0	R/W	Port 0C bit 0
P0C1	FLG	0.72H.1	R/W	Port 0C bit 1
P0C2	FLG	0.72H.2	R/W	Port 0C bit 2
P0C3	FLG	0.72H.3	R/W	Port 0C bit 3
PODO	FLG	0.73H.0	R/W	Port 0D bit 0
POD 1	FLG	0.73H.1	R/W	Port 0D bit 1
P0D2	FLG	0.73H.2	R/W	Port 0D bit 2
P0D3	FLG	0.73H.3	R/W	Port 0D bit 3
P1A0	FLG	1.70H.0	R	Port 1A bit 0
P1A1	FLG	1.70H.1	R	Port 1A bit 1
P1A2	FLG	1.70H.2	R	Port 1A bit 2
P1A3	FLG	1.70H.3	R	Port 1A bit 3
P1B0	FLG	1.71H.0	R	Port 1B bit 0
P1B1	FLG	1,71H.1	R	Port 1B bit 1
P1B2	FLG	1.71H.2	R	Port 1B bit 2
P1B3	FLG	1.71H.3	R	Port 1B bit 3
DARH	MEM	1.72H	R/W	D/A conversion data bit 4 and bit 5



Table 7-2 List of reserved symbols (3/4)

NAME	ATTRIBUTE	VALUE	R/W	DESCRIPTION
DARL	MEM	1.73H	R/W	D/A conversion data bit 3 to bit 0
DACCMP	FLG	1.73H.0	R	Result of comparison
SP	MEM	0.81H	R/W	Stack pointer
SIOTS	FLG	0.82H.3	R/W	SIO operating status
SIOHIZ	FLG	0.82H.2	R/W	Status of SO pin
SIOCK1	FLG	0.82H.1	R/W	Selection of serial clock
SIOCK0	FLG	0.82H.0	R/W	Selection of serial clock
INT1	FLG	0.8FH.2	R	Status of INT ₁ pin
INTO	FLG	0.8FH.1	R	Status of INT ₀ pin
ZCROSS	FLG	0.8FH.0	R/W	Status of zero-cross detection circuit
TM1EN	FLG	0.91H.3	R/W	Timer 1 permit
TM1RES	FLG	0.91H.2	R/W	Timer 1 reset
TM1CK1	FLG	0.91H.1	R/W	Timer 1 clock selection
TM1CK0	FLG	0.91H.0	R/W	Timer 1 clock selection
TM2EN	FLG	0.92H.3	R/W	Timer 2 permit
TM2RES	FLG	0.92H.2	R/W	Timer 2 reset
TM2CK1	FLG	0.92H.1	R/W	Timer 2 clock selection
TM2CK0	FLG	0.92H.0	R/W	Timer 2 clock selection
IEG1	FLG	0.9FH.2	R/W	INT1 edge selection
IEG0	FLG	0.9FH.1	R/W	INTO edge selection
AMP1EN	FLG	0.A1H.3	R/W	AMP1 permit
AMP1MD2	FLG	0.A1H.2	R/W	Mode selection
AMP2MD1	FLG	0.A2H.1	R/W	Be sure to write "O"
AMP2MD0	FLG	0.A2H.0	R/W	SAMPLE-HOLD selection
CMPEN	FLG	0.A3H.3	R/W	Comparator permit
DACEN	FLG	0.A3H.2	R/W	D/A converter permit
ADCCH1	FLG	0.A3H.1	R/W	Comparator input selection
ADCCH0	FLG	0.A3H.0	R/W	Comparator input selection
PODGIO	FLG	0.A7H,3	R/W	Port 0D I/O selection
P0DGIO	FLG	0.A7H.2	R/W	Port OC I/O selection
POBGIO	FLG	0.A7H.1	R/W	Port 0B I/O selection
P0AGIO	FLG	0.A7H,0	R/W	Port 0A I/O selection



Table 7-2 List of reserved symbols (4/4)

NAME	ATTRIBUTE	VALUE	R/W	DESCRIPTION
IPTM2	FLG	0.AEH.1	R/W	INTTM2 permit flag
IP1	FLG	0.AEH.0	R/W	INT1 permit flag
IPSIO	FLG	0.AFH.3	R/W	INTSIO permit flag
IPO .	FLG	FLG 0.AFH.2 R/W INTO perr		INTO permit flag
IPTM1	FLG	0.AFH.1	R/W	INTTM1 permit flag
LCDOFF	FLG	0.B1H.3	R/W	LCD segment/port selection
LCDMD2	FLG	0.B1H.2	R/W	LCD mode selection
LCDMD1	FLG	0.B1H.1	R/W	LCD mode selection
LCDMD0	FLG	0.B1H.0	R/W	LCD mode selection
LCDEN	FLG	0.B2H.3	R/W	ICD segment output permit
PTOUTON	FLG	0.B7H.0	: R/W	PTOUT output permit
SIOON	FLG	0.B7H.1	R/W	SIO output permit
IRQTM2	FLG	0.BEH.1	R/W	INTTM2 interrupt request
IRQ1	FLG	0.BEH.0	R/W	INT1 interrupt request
IRQSIO	FLG	0.BFG.3	R/W	INTSIO interrupt request
IRQ0	FLG.	0.BFH.2	R/W	INTO interrupt request
IRQTM1	FLG	0.BFG.1	R/W	INTTM1 interrupt request
DBF	DAT	OFH	R/W	GET/PUT instruction operand
IX	DAT	01H	R/W	Index register
AR	DAT	00Н	R/W	Address register
SIOSFR	DAT	01H	R/W	SIO register
TM1M	DAT	02H	w	Timer 1 modulo register
TM2M	DAT	03 H	w	Timer 2 modulo register
TMC	DAT	41H	R	Timer count register

Note: "W. XYH. Z" in the value field indicates

W Bank

X Row address
Y Colum address
Z Bit



8. INSTRUCTION SET

Table 8-1 List of instruction sets

	b15					
b14 to b11	//		0			1
BIN	HEX					
0000	0	ADD r,	m	ADD	m,	# i
0001	1	SUB r,	m	SUB	m,	#i
0010	2	ADDC r,	m	ADDC	m,	#i
0011	3	SUBC r,	m	SUBC	m,	# i
0100	4	AND r,	m	AND	m,	# i
0101	5	XOR r,	m	XOR	m,	#i
0110	6	OR r,	m	OR	m,	# i
01111	7	INC IX MOVT DI BR @ CALL @ RET RETSK EI DI RETI PUSH AI POP AI GET DI PUT p, PEEK W	BF, @AR AR AR			
1000	8	LD r,	m	ST	m,	r
1001	9	SKE m	, #i	SKGE	m,	#i
1010	Α	MOV @	r, m	MOV	m,	@ r
1011	В	SKNE m,	, #i	SKLT	m,	# i
1100	С	BR ad	dr	CALL	addr	
1101	D			MOV	m,	# i
1110	Е			SKT	m,	#n
1111	F			SKF	m,	#n



Table 8-2 List of INSTRUCTIONS

Lege	ends		
R RF AR IX DBF WR MP	: Window register : Memory pointer MPE : Memory pointer enable flag : Peripheral Peripheral address ph : Peripheral address high (row address! 3 bits	PC SP STACK BANK (AR) rom INTEF i n addr a _H a _N a _L CY CMP s h	Program counter Stack pointer Stack specified by (SP) Bank register One of program memory data specified by (AR) Interrupt enable flag Immediate data : 4 bits One of program memory address : 11 bits Program memory address high : 3 bits Program memory address high : 3 bits Program memory address high : 4 bits Program memory address low : 4 bits Carry flag Compare flag Stop release condition Halt release condition Address of M.R.RF Contents of M.R.RF, AR, IX, DBF, WR, PE
	pt. Peripheral address low (column address) 4 bits		

e tion	1			0		Machin	e code	
Instruction group	Mnemonic	Operand	Function	Operation	Opration code	3bits	4bits	4bits
		r,m	Add memory to register R , $CY \leftarrow (R) + (M)$		00000	m _H	m_L	r
ı	ADD	m,#i	Add immediate data to memory	M. CY← (M) +i	10000	mн	mL	i
Addition		r,m	Add memory to register with carry	$R. CY \leftarrow (R) + (M + (CY))$	00010	m _H	mL	r
V∰ V	ADDC	m.#i	Add immediate data to memory with carry	R. CY← (M) +i+ (CY)	10010	m _H	mL	i
		AR	Increment address register	AR←AR+1	00111	000	1001	0000
	INC	IX	Increment index register	IX+1X+1	00111	000	1000	0000
٤	CUID	r,m	Subtract memory from register	R. CY+ (R) = (M)	00001	m _H	mL	r
Subtraction	SUB	m,#i	Subtract immediate data from memory	M. CY← (M) +i	10001	m _H	mL	i
4	auna	r.m	Subtract memory from register with borrow	$R. CY \leftarrow (R) - (M) = (CY)$	00011	m _H	mL	r
x.	SUBC	m, #i	Subtract immediate data from memory with borrow	M. CY← (M) ~i~ (CY)	10011	m _H	mL	i
_	SKE	m,#i	Skip if memory equal to immediate data	M-ilskip if zero	01001	m _H	mL	i
Comparison	SKGE	m,#i	Skip if memory greater than or equal to immediate data	M-i,skip if not borrow	11001	mH	mL	i
ашо	SKLT	m,#i	Skip if memory less than immediate data	M-1.skip if borrow	11011	m _H	mL	i
اتا	SKNE	m,#i	Skip if memory not equal to immediate data	M-i.skip if not zero	01011	m _H	m _L	i,
		m,#i	Logical AND of memory and immediate data	M← (M) AND i	10100	m _H	mL	i
operation	AND	r,m	Logical AND of register and memory	R← (R) AND (M)	00100	m ^H	mL	7
Per s		m.#i	Logical OR of memory and immediate data	M← (M) OR i	10110	m _H	m _L	j
ca	OR	r.m	Logical OR of register and memory	R← (R) OR (M)	00110	m _H	m _L	Т
Logical		m.#i	Logical XOR of memory and immediate data	M← (M) XOR i	10101	m _H	mL	i.
	XOR	r,m	Logical XOR of register and memory	R← (R) XOR (M:	90101	m _H	mL	r
	LD	r,m	Load memory to register	R← (M)	01000	m _H	mı	r
	ST	m,r	Store register to memory	(M) ←R	11000	mH	mı	r
		€r,m	Move memory to destination memory referring to register	if MPE = 1, $\{(MP), (R)\} \leftarrow (M)$ if MPE = 0, $\{(m_H), (R)\} \leftarrow (M)$	01010	mH	m _L	r
sfer	MOV	m, er	Move source memory referring to register to memory	if MPE = 1, M \leftarrow [(MP), (R)] if MPE = 0, M \leftarrow [(m _H), (R)]	11010	mя	աւ	r
Transfer		m,#i	Move immediate data to memory	M←i	11101	m _H	m _L	i
	MOVT	DBF. éAR	Move ROM data from the address specified in AR to DBF	sp←(sp) -1.STACK←PC DBF←(AR) rom, PC←STACK,sp←(sp)+1	00111	000	0001	0000
	PUSH	AR	Decrement SP, then move AR to stack top	SP←(SP) -1,STACK←AR	00111	000	1101	0000
	POP	AR	Move stack top to AR, then increment SP	AR←STACK.SP←SP+1	00111	000	1100	0000
1	PEEK	WR.RA	Get RA from RF through WR	WR←(RF)	00111	rf _H	0011	rf _L



ction					1	Machin	e code	\Box
Instru	Mnemonac	Operand	Function	Operation	Opration code	3bits	4bits	4bits
į	POKE	RA,WR	Put data on WR into RA of RF	(RF)←WR	00111	rf _H	0010	тfL
Transfer	GET	DBF.p	Get peripheral data to DBF	DBF←p	00111	PH	1011	PL
Ĕ	PUT	p,DBF	Put data in DBF to peripheral	p←DBF	00111	PH	1010	PL
Decision	SKT	m,#n	Test memory bits, then skip if all bits specified are true	CMP←0 skip if M(N) = all "1"	11110	m _H	mL	n
	SKF	m, #n	Test memory bits, then skip if all bits specified are false	CMP←0 skip if M(N) = all "0"	11111	m _H	mL	л
Branch	BR	addr	Jump to the address	PC←ADDR	01100	a _H	a _M	a _L
Bra	DK .	@AR	Jump to the address specified in AR	PC←AR	00111	000	0100	0000
Shift	RORC	r	Rotate register right with carry $(CY) \rightarrow (R) \rightarrow CY$		00111	000	0111	r
	CALL	addr	Call subroutine	SP←(SP) -1 STACK←((PC)+1), PC←ADDR	11100	a _H	a _M	a _L
Subroutine	CALL	@AR	Call subroutine specified in AR	SP←(SP) - 1, STACK←((PC) + 1), PC←(AR)	00111	000	0101	0000
Seb	RET		Return to main routine from subroutine	PC←(STACK),SP←(SP)+1	00111	000	1110	0000
	RETSK		Return to main routine from subroutine, then skip unconditionary	PC←(STACK),SP←(SP)+1 and skip	00111	901	1110	0000
	RETI		return to main routine from interrupt service routine PC←(STACK) .SP BANK←(interrupt		00111	100	1110	0000
Interrupt	EI		Enable interrupt	INTE flag←1	00111	000	1111	0000
at a	DI		Disable interrupt INTE flag ←0		00111	001	1111	0000
ا ۾ ا	STOP	s	Stop clock	STOP	00111	010	1111	s
Others	HALT	h	Halt the CPU, restart by condition H	HALT	00111	011	1111	h
Ľ	NOP		No operation	No operation	00112	100	1111	0000



9. ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (Ta = 25 °C)

Supply Voltage	V_{DD}	-0.3 to +7.0	٧	* .	
Input Voltage	VI	-0.3 to V _{DD} +0.3	V	POA	(1)
		-0.3 to +11	٧		(2)
		-0.3 to V _{DD} + 0.3	V	All pins other t	than POA
Output Voltage	V _O	-0.3 to V _{DD} +0.3	٧	P0A	(1)
		-0.3 to +11	V		(2)
		-0.3 to V _{LCD} +0.3	٧	Segment/comr	non pins
		-0.3 to V _{DD} +0.3	٧	Pins other than	above
High-Level Output Current	Іон	-5	mΑ	1 pin	
		-20	mΑ	Total of all pir	15
Low-Level Output Current	loL	15	mΑ	1 pin	P0A, P0D
		30	mΑ		POB, POC
		100	mΑ	Total of all pir	ns
Operating Temperature	Topt	-40 to +85	°C		
Storage Temperature	T _{stq}	-65 to +150	°C		
Power Consumption	Pd	190	mW	T _a = 85 °C	

Remarks: 1. N-ch open/drain output plus built-in pull-up resistor output

2. N-ch open/drain input/output

CAPACITY (Ta = 25 °C, VDD = 0 V)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITION
Input Capacity	CIN			15	pF	f = 1 MHz
Output Capacity	COUT			15	pF	Pins other than those measured: 0 V
Input/Output Capacity	CIO			15	pF	



DC CHARACTERISTICS ($T_a = -40 \text{ to } +85 \,^{\circ}\text{C}$, $V_{DD} = 3.0 \text{ to } 6.0 \text{ V}$)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITION		
	V _{IH1}	0.8 V _{DD}		9	V	At SI or SCK	input	
High-Level Input Voltage	V _{1H2}	0.7 V _{DD}		9	٧	At POA input	1	
mign-Lever input voltage	V _{IH3}	0.8 V _{DD}		V _{DD}	٧	INT ₁ , INT ₁ ,	RESET	
	V _{IH4}	0.7 V _{DD}		V _{DD}	٧	Pins other th	an above	
Law Law Law Malawa	V _{IL1}	0		0.2 V _{DD}	V	SI, SCK, INT	O, INT ₁ , RESET	
Low-Level Input Voltage	V _{IL2}	0		0.3 V _{DD}	V	Pins other the	an above	
High-Level Output Voltage	Voн	V _{DD} -2.0	V _{DD} −0.4		٧		V _{DD} = 4.5 to 6.0 V I _{OH} = -1 mA	
		V _{DD} 1.0	V _{DD} -0.04		٧		I _{OH} = -100 μA	
			0.85	2.0	٧	POB, POC	V _{DD} = 4.5 to 6.0 V I _{OL} = 15 mA	
			0.06	0.5	٧		I _{OL} = 600 μA	
Low-Level Output Voltage	VOL		0.85	2.0	>		V _{DD} = 4.5 to 6.0 V I _{OL} = 10 mA	
			0.15	0.4	V	POA, POD	V _{DD} = 4.5 to 6.0 V I _{OL} = 1.6 mA	
			0.04	0.5	v		I _{OL} = 400 μA	
Ulah Lauri	¹ LIH1			3	μА	Other than XI and XO	V _{IN} = V _{DD}	
High-Level Input Leak Current	LIH2			10	μА	XI, XO	V _{IN} = V _{DD}	
	ILIH3			10	μΑ	POA (3)	V _{IN} = 9 V	
Low-Level Input Leak Current	LIL			-3	μΑ	Other than XI and XO	V _{IN} = 0 V	
				-10	μА	XI, XO	V _{IN} = 0 V	
High-Level Output Leak Current	ILOH1	-,		3	μА		V _{OUT} = V _{DD}	
	ILOH2			10	μΑ	POA (3)	V _{OUT} = 9 V	
Low-Level Output Leak Current	LOL			-3	μΑ		V _{OUT} = 0 V	
Input pin with built-in resistor (pull up/pull down)		35	65	110	kΩ	INTO, INT1,	P1 A, P1 B	
Input pin with built-in resistor (pull	up)	35	65	110	kΩ	RESET		
Input pin with built-in resistor (pull	down)	7	15	26.5	kΩ	P0A		
N .	l _{DD1}		1500	4500	μА	Operation	V _{DD} = 5 V ± 10 % f _{CC} = 8 MHz	
	551		250	750	μА	mode	V _{DD} = 3 V ± 10 % f _{CC} = 2 MHz	
Supply Current (4)	I _{DD2}		550	1600	μΑ	Halt mode	V _{DD} = 5 V ± 10 % f _{CC} = 8 MHz	
	- 502		110	330	μА		V _{DD} = 3 V ± 10 % f _{CC} = 2 MHz	
	lona		0,1	10	μΑ	Stop mode	V _{DD} = 5 V ± 10 %	
	DD3		0.1	5	μΑ	atop mode	V _{DD} = 3 V ± 10 %	



CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITION	
V _{LCD} Voltage Range	VLCD	3.0		V _{DD}	V		
Common Output Impedance (5)	RCOM		40		kΩ		V _{DD} = 4.5 to 6.0 V
Segment Output Impedance (5)	R _{SEG1}		40		kΩ	At LCD drive	V _{DD} = 4.5 to 6.0 V
	R _{SEG2}		5		kΩ	At port operation	Total output of all segment pins Current 2 mA or less VDD = VLCD = 4.5 to 6.0 V
Resistance Between V _{LCD} and R _{VLC}	 		100		kΩ	When norma	ol
		3.0		kΩ	When switching		

Remarks: 3. When N-ch open/drain input/output is selected

- 4. The current that flows through the built-in pull-up or pull-down resistor is excluded
- 5. 3.5 $k\Omega$ (typ.) when switching between the common and segment output.

AMPLIFIER CHARACTERISTICS (T_a = -40 = +85 °C, V_{DD} = 4.5 to 6.0 V)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITION
Input Offset Voltage	vos		±6	±18	mV	Normal amplifier mode
n-phase Input Voltage	VICM	0.0		3.6	V	V _{DD} = 5.0 V
Output Voltage Range	Vout	0.12		4.8	V	V _{DD} = 5.0 V, I _{OUT} = 0 μA
Unity Gain Frequency	fo		1.5		MHz	
Large Amplitude Gain	Av		85		dB	V _{DD} = 5.0 V
Output Current	Ιουτ	-50		100	μА	V _{DD} = 5.0 V
CMRR			75		dB	
SVRR		-	-60		dB	
Through Rate		1.0			V/μs	
Hold Time	†SAMP		0.05		ms	Sample/hold amplifier mode
Input/Output Voltage Error	VDIF		±6	±18	mV	Sample/hold amplifier mode
Input Voltage Range	VIN		0.12	2.5	V	Sample/hold amplifier mode
Supply Current	IAMP	<u> </u>	230	500	μА	

COMPARATOR CHARACTERISTICS (T_a = -40 to +85 °C, V_{DD} = 4.5 to 6.0 V)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	דומט	CONDITION
Input Voltage Range	VIN	VSS		V _{DD}	v	
Response Speed (6)	†COMP	2			IC	
Power Consumption	VCOMP		100		μА	V _{DD} = 5.0 V
Absolute Accuracy	VIT		±8.0	±15.0	mV	
Input Resolution	VRE		3.0		mV	



D/A CONVERTER CHARACTERISTICS (T $_{a}$ = -40 to +85 °C, $V_{\rm DD}$ = 4.5 to 6.0 V, $V_{\rm REFH}$ = $V_{\rm DD}$, $V_{\rm REFL}$ = 0 V)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITION
Resolution		6	6	6	Bit	
Linearity				±0.5	LSB	
D/A Conversion Time (6)	tCONV	2			IC	At no output load
DAC Current	IDAC		220	390	μА	
A/D Conversion Time (6)		4			IC	

Remarks 6: IC indicates "instruction cycle".

ZERO-CROSS CHARACTERISTICS ($T_a = -40 \text{ to } +85 \,^{\circ}\text{C}$, $V_{DD} = 4.5 \text{ to } 6.0 \text{ V}$)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITION
Detection Input Level	VZX	0.8	3,0		V _{Р-Р}	Input AC
Accuracy	AZX		±120		mV	50/60 Hz
Detection Input Frequency	fzx	0.04	1		kHz	

DATA MEMORY DATA RETENTION CHARACTERISTICS AT LOW SUPPLY VOLTAGE IN STOP MODE (T $_{a}$ = $-40\ to$ $+85\ ^{\circ}\text{C})$

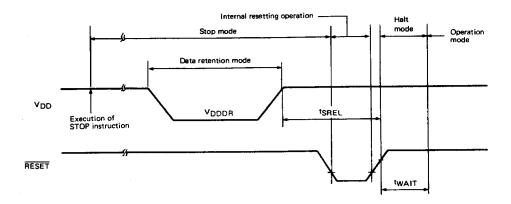
CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITION
Data Retention Supply Voltage	VDDDR	2.0		6.0	v	
Data Retention Supply Current	IDDDR		0.1	5.0	μА	V _{DDDR} = 2.0 V
Release Signal Set Time	tSREL .	0			μs	
Wait Time for Stable Oscillation			2 ^{†9} /fx		ms	Release by RESET (7)
wait time for Stable Oscillation	TIAW		(8)		ms	Release by interrupt request

Remarks: 7. fx indicates the oscillator frequency.

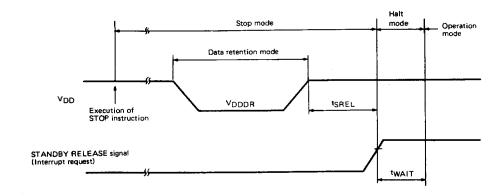
8. According to the timer 2 value.



Data Retention Timing (Stop Mode Release by Reset)



Data Retention Timing (Stand-by Release Signal: Stop Mode Release)





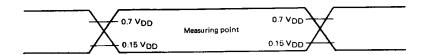
AC CHARACTERISTICS (T_a = -40 to +85 °C, V_{DD} = 3.0 to 6.0 V)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITION	
Internal Clock Cycle Time	•	2		30	μs	V _{DD} = 4.5 to	6.0 V
Internal Clock Cycle Time	tCY	8		30	μ5		
Event Input Frequency	fPO	0		1000	kHz		V _{DD} = 4.5 to 6.0 V
Event input Frequency		0		350	kHz	duty = 50 %	
Event Input Rising/Falling Time	tPOR tPOF			0.1	μs	Excluding zer	ro-cross mode
Event Input High/Low Level	tPOH .	0.5			μs	V _{DD} = 4.5 to	6.0 V
Width	^t POL	1.45	1.		μs		
SCK Input Cycle Time (9)		2.0			μs	At data input	
	[‡] KCY	10.0			μs	At data output	V _{DD} = 4.5 to 6.0 V
		5.0			μs	At data input	
		13.0			μs	At data output	
	^t KH ^t KL	1.0			μs	At data input	45. 004
SCK Input High/Low Level		5.0			μs	At data Output	V _{DD} = 4.5 to 6.0 V
Width (9)		2.5			μς	At data input	
		6.5			μs	At data Output	
SI Setup Time (to SCK+)	tsik	100			μς		
SI Hold Time (to SCK†)	tKSI	100			μs		_
SCK+ → SO output delay time (9)	tKSO			4.5	μs	Cp = 100 pF	
INT high/low level width	tIOH tIOL	10			μs		
RESET low level width	tRSL	10	1	1	μs		

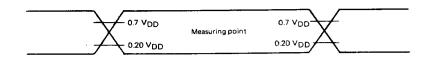
 $\textbf{Remarks 9:} \ \ \text{For SI, SO and} \ \ \overline{\textbf{SCK}} \ pins, \ the \ \textbf{N-ch open/drain output plus built-in pull-up resistor input/output}.$



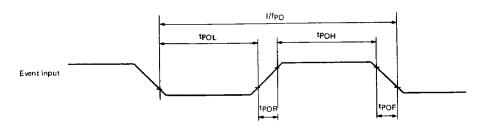
AC Timing Measuring Point (INT0, INT1, SI, $\overline{\text{SCK}}$ and SO Pins)



AC Timing Measuring Point (Pins other than INT $_0$, INT $_1$, SI, $\overline{\text{SCK}}$ SO)

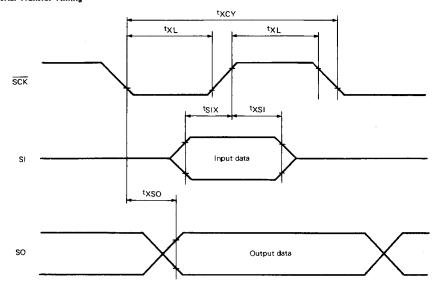


Event Input Timing

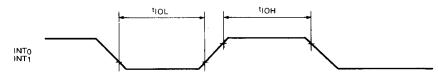




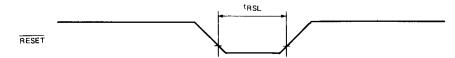
Serial Transfer Timing



INT Input Timing



RESET Input Timing





10. RECOMMENDED SOLDERING CONDITIONS

The following conditions (see table below) must be met when soldering this product.

Please consult with our sales offices in case other soldering process is used, or in case soldering is done under different conditions.

TYPES OF SURFACE MOUNT DEVICE

For more details, refer to our document "SMT MANUAL" (IEI-1207). uPD17102G

Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak package's surface temperature: 230 °C or below, Reflow time: 30 seconds or below (210 °C or higher), Number of reflow process: 1, Exposure limit*: None	IR30-00
VPS	Peak package's surface temperature: 215 °C or below, Reflow time: 40 seconds or below (200 °C or higher), Number of reflow process: 1, Exposure limit*: None	VP15-00
Wave soldering	Solder temperature: 260 °C or below, Flow time: 10 seconds or below, Number of flow process: 1, Exposure limit*: None	WS60-00
Partial heating method	Terminal temperature : 300 °C or below, Flow time : 10 seconds or below, Exposure limit* : None	

Exposure limit before soldering after dry-pack package is opened.
 Storage conditions: 25 °C and relative humidity at 65 % or less.

Note: Do not apply more than a single process at once, except for "Partial heating method".



11. DEVELOPMENT SUPPORT TOOLS

The following tools are supported for developing systems using the $\mu PD17102$ chip.

Hard-	IE-17K	IE-17K is an in-circuit emulator available for all the μ PD17000 Series chips. For the μ PD17102 chip, use IE-17K and the optional SE-17102 together. When connected to a personal computer, IE-17K adds and modifies programs in real time. A PC-9801 personal computer runs the support software SIMPLEHOST, providing a more advanced development environment.								
ware	SE-17102	SE-17102 is an emulation board (SE board) used to evaluate the system by mounting the program developed by IE-17K and loading the board instead of the µPD17102 to the system.								
	EP-17102G	Probe used to connect the target system.								
	μPD17000 Series	Host machine	os	Order name (product name)						
	Assembler AS17K	PC-9800 Series (excluding PC-98LT)	MS-DOS TM (Ver 2.11 or later)	μS5A1AS17K (8" 2D) μS5A10AS17K (5" 2HD)						
Soft- ware	Device file	Used together with the μPE AS17K (for μPD17102 only	μS5A1AS17102 (8"2D) μS5A10AS17102 (5" 2HD)							
	SIMPLEHOST*	Program to support man-n necting PC-9801 to IE-17K MS-WINDOWS TM is require	μS5A1IE17K (8" 2D) μS5A10IE17K (5" 2HD)							

^{*:} Under development

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